



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® SC-70					
Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
BOND INT	120	20,000	200 °C + N2	0	0.00
HAST	165	16,500	130 °C, 85 % RH	0	0.00
Pressure Pot	165	16,500	121°, 15 PSIG	0	0.00
Solderability	20	480	883 M2003	0	0.00
Temp Cycle	165	82,500	- 65 °C - 150 °C	0	0.00